

2SK1316(L), 2SK1316(S)

Silicon N Channel MOS FET

REJ03G0928-0200 (Previous: ADE-208-1267) Rev.2.00 Sep 07, 2005

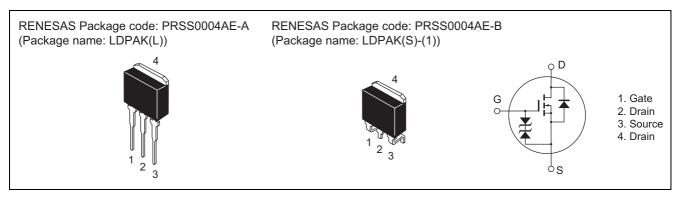
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter and motor driver

Outline





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	500	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	ID	8	A
Drain peak current	I _{D(pulse)} * ¹	32	А
Body to drain diode reverse drain current	I _{DR}	8	А
Channel dissipation	Pch* ²	60	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at $T_c = 25^{\circ}C$

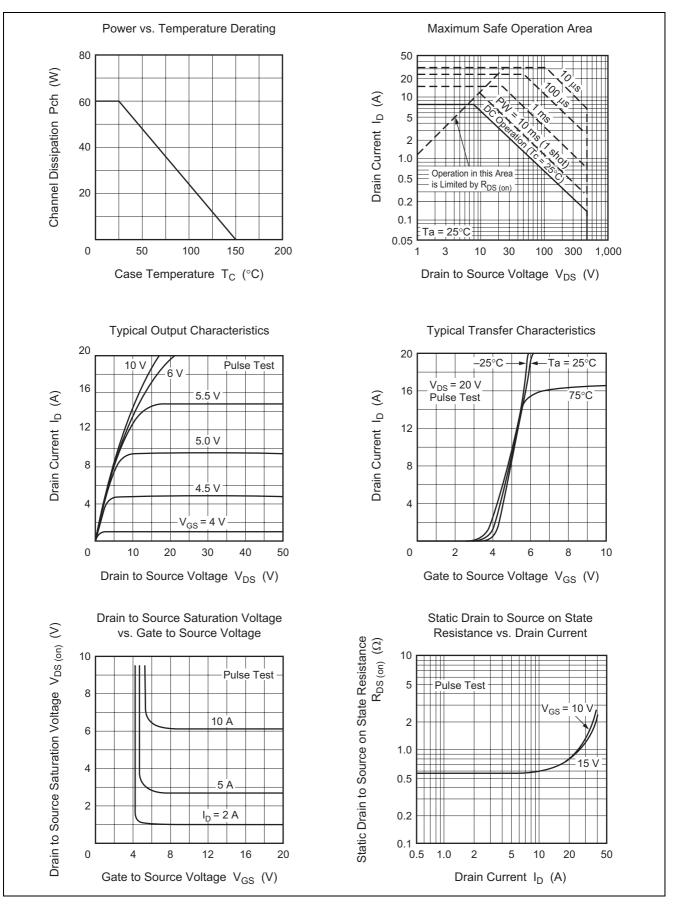
Electrical Characteristics

						(Ta = 25°C)
ltem	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	500	_	_	V	I _D = 10 mA, V _{GS} = 0
Gate to source breakdown voltage	V _{(BR)GSS}	±30	—	_	V	I_{G} = ±100 µA, V _{DS} = 0
Gate to source leak current	I _{GSS}	_	—	±10	μΑ	V_{GS} = ±25 V, V_{DS} = 0
Zero gate voltage drain current	I _{DSS}	_	—	250	μΑ	V _{DS} = 400 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	2.0	—	3.0	V	I _D = 1 mA, V _{DS} = 10 V
Static drain to source on state	R _{DS(on)}		0.60	0.8	Ω	I_D = 4 A, V_{GS} = 10 V * ³
resistance						
Forward transfer admittance	y _{fs}	4.5	7.5	—	S	I_D = 4 A, V_{DS} = 10 V * ³
Input capacitance	Ciss	_	1150	—	pF	V _{DS} = 10 V, V _{GS} = 0, f = 1 MHz
Output capacitance	Coss	_	340	_	pF	
Reverse transfer capacitance	Crss	_	55	_	pF	
Turn-on delay time	t _{d(on)}	_	17	_	ns	I_D = 4 A, V _{GS} = 10 V, R _L = 7.5 Ω
Rise time	tr		55	_	ns	
Turn-off delay time	t _{d(off)}		100	_	ns	
Fall time	t _f		45	_	ns	
Body to drain diode forward voltage	V _{DF}		0.9	—	V	I _F = 8 A, V _{GS} = 0
Body to drain diode reverse recovery	t _{rr}	_	350	—	ns	I _F = 8 A, V _{GS} = 0,
time						di _F /dt = 100 A/µs

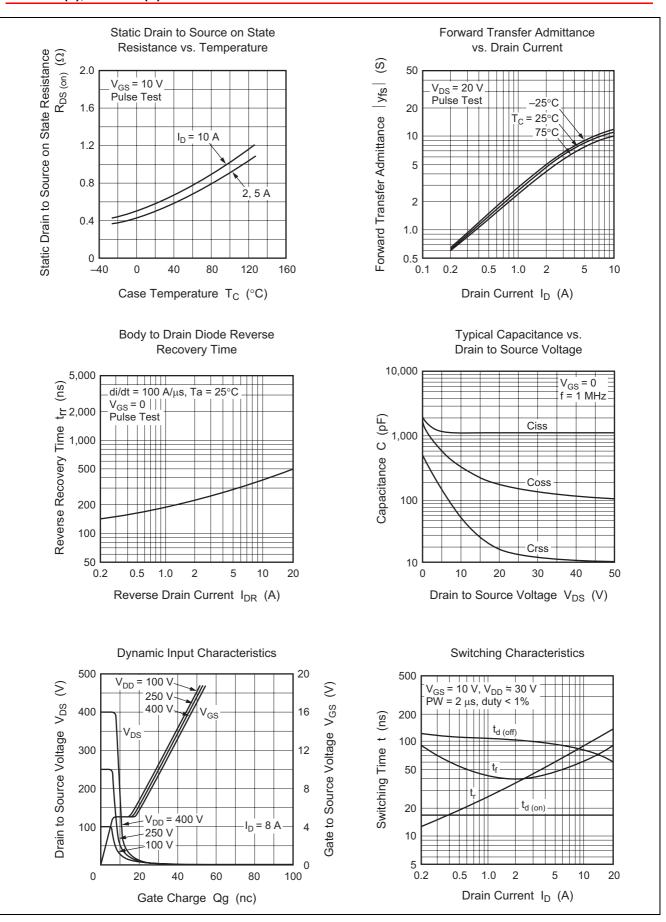
Note: 3. Pulse test

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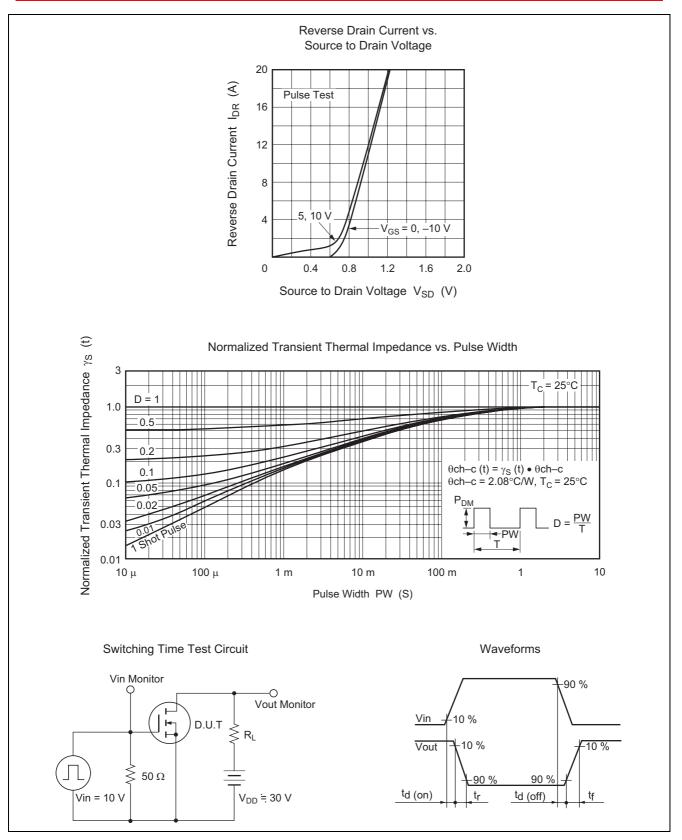
Main Characteristics





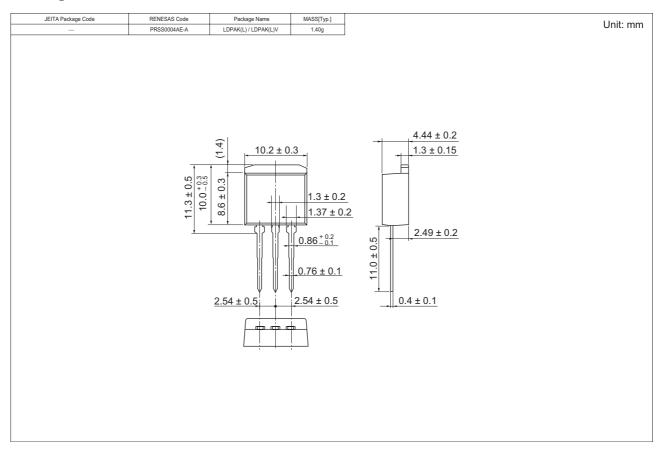


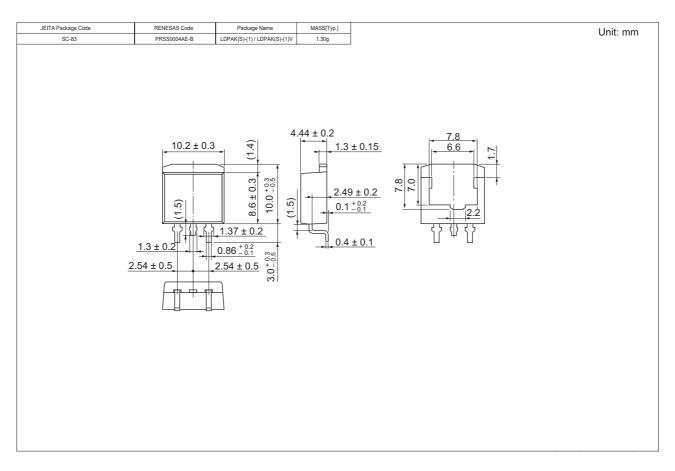






Package Dimensions







Ordering Information

Part Name	Quantity	Shipping Container
2SK1316L-E	500 pcs	Box (Sack)
2SK1316STL-E	1000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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